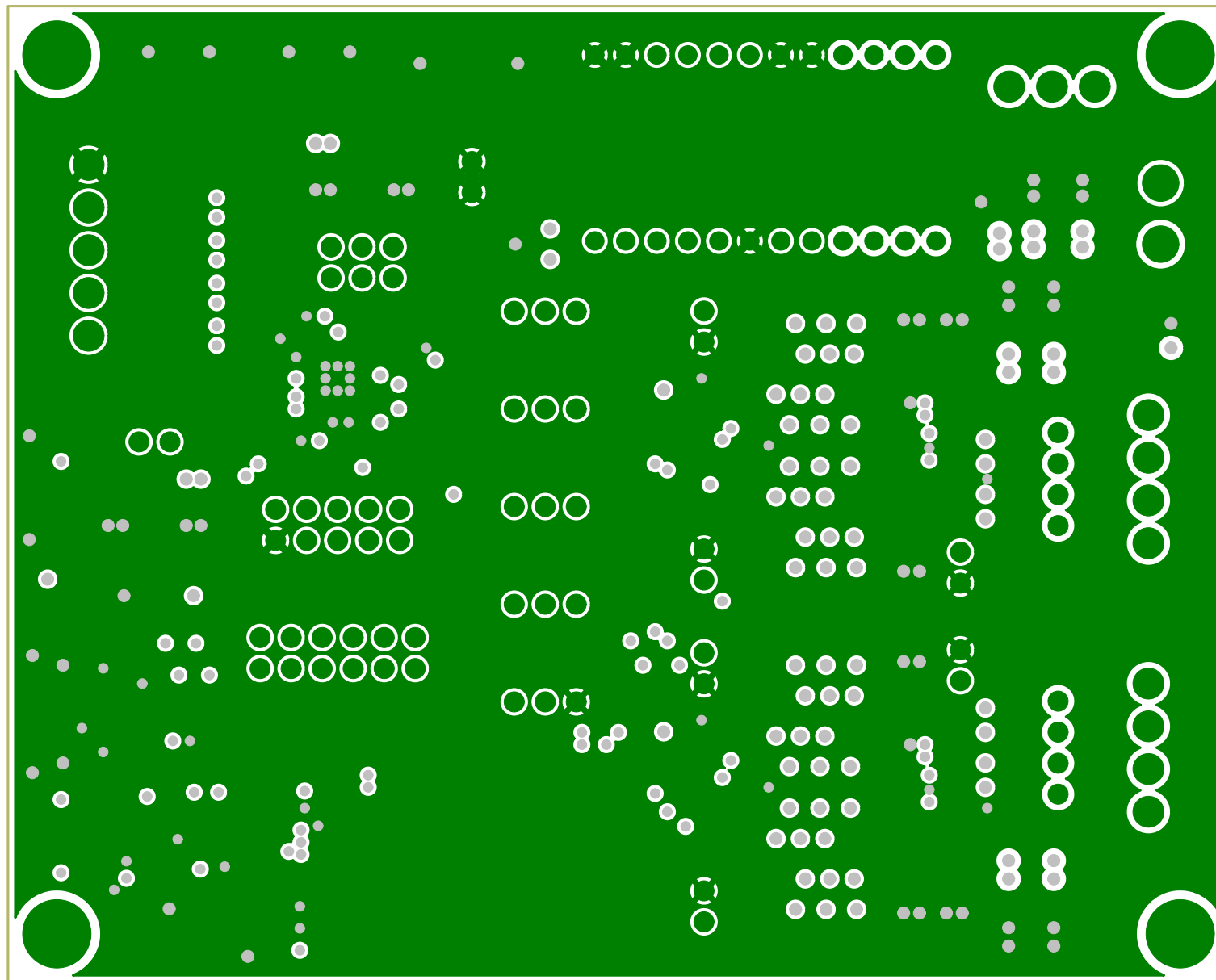


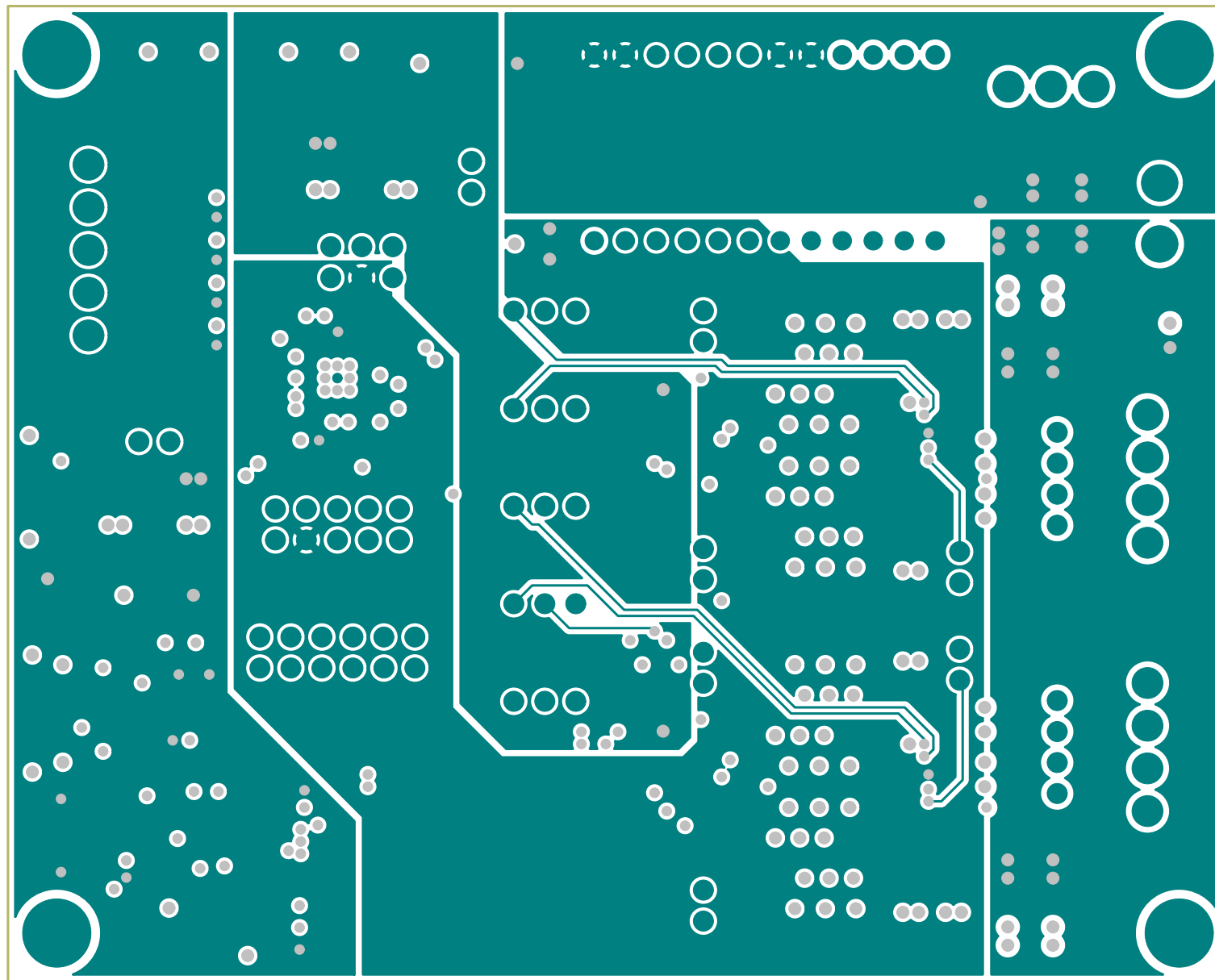
CCTV Reference Design 24.03.2011

ROUTING TOP (L1) 100x80MM



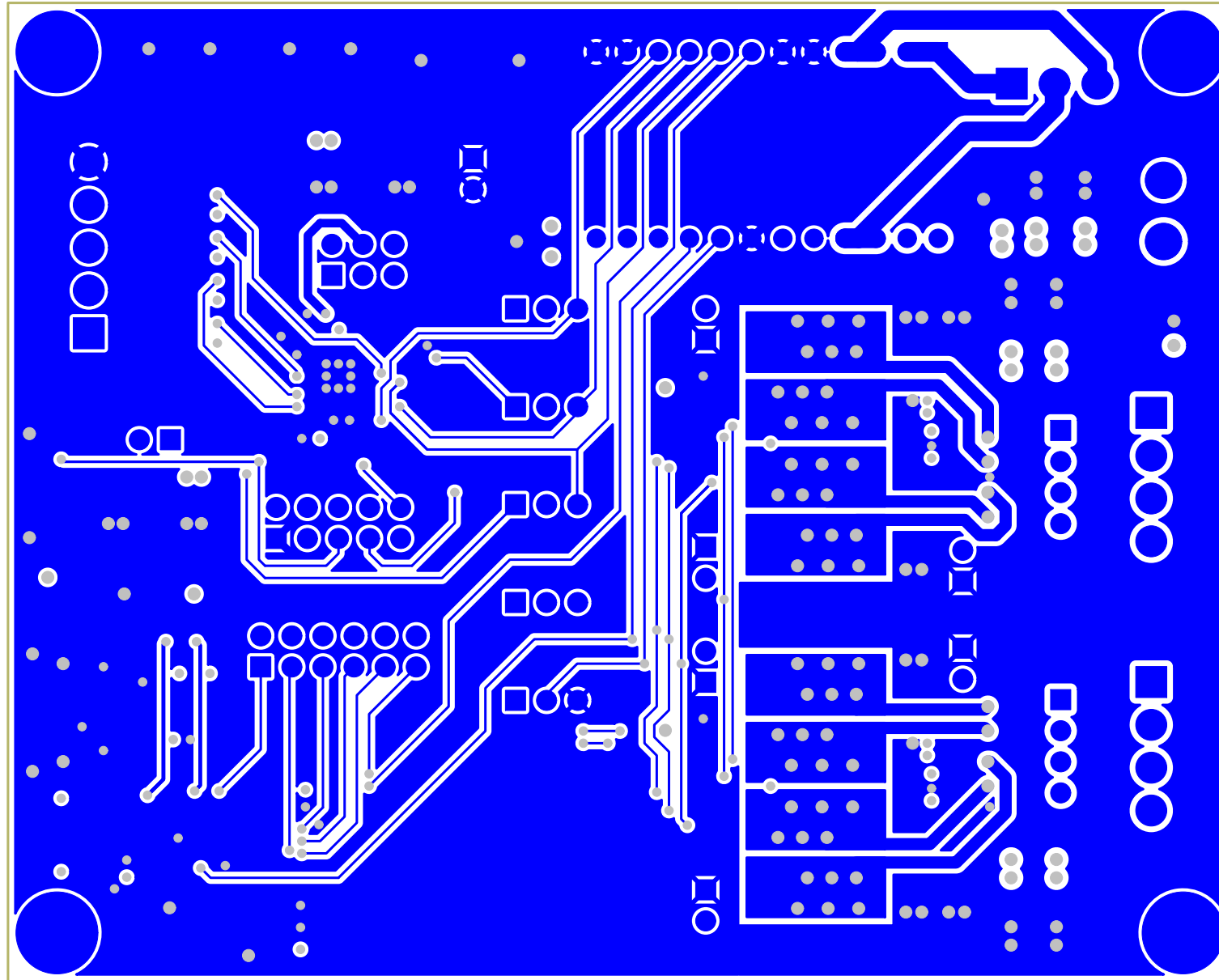
CCTV Reference Design 24.03.2011

GROUND LAYER 2 (L2)



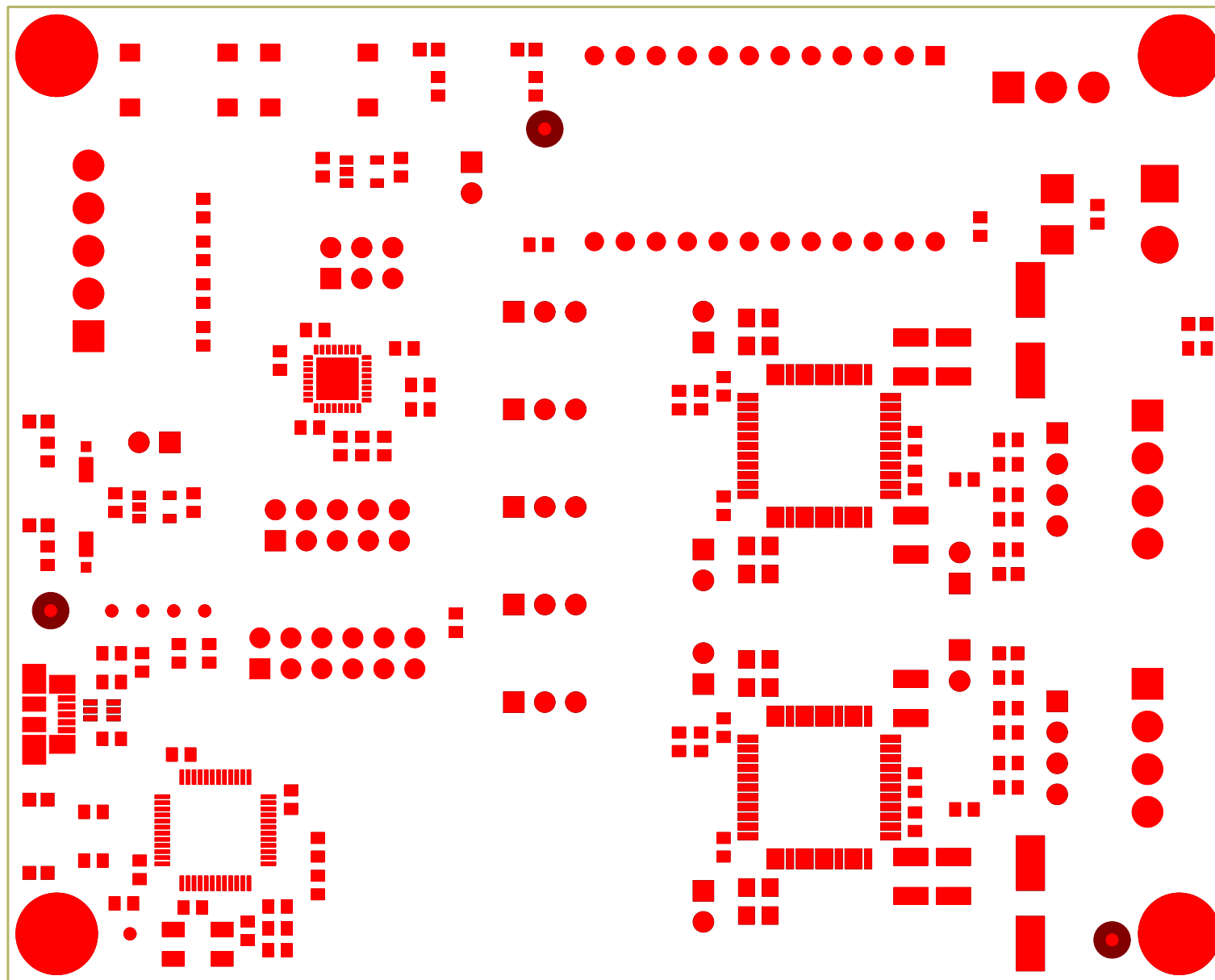
CCTV Reference Design 24.03.2011

POWER LAYER 3 (L3)



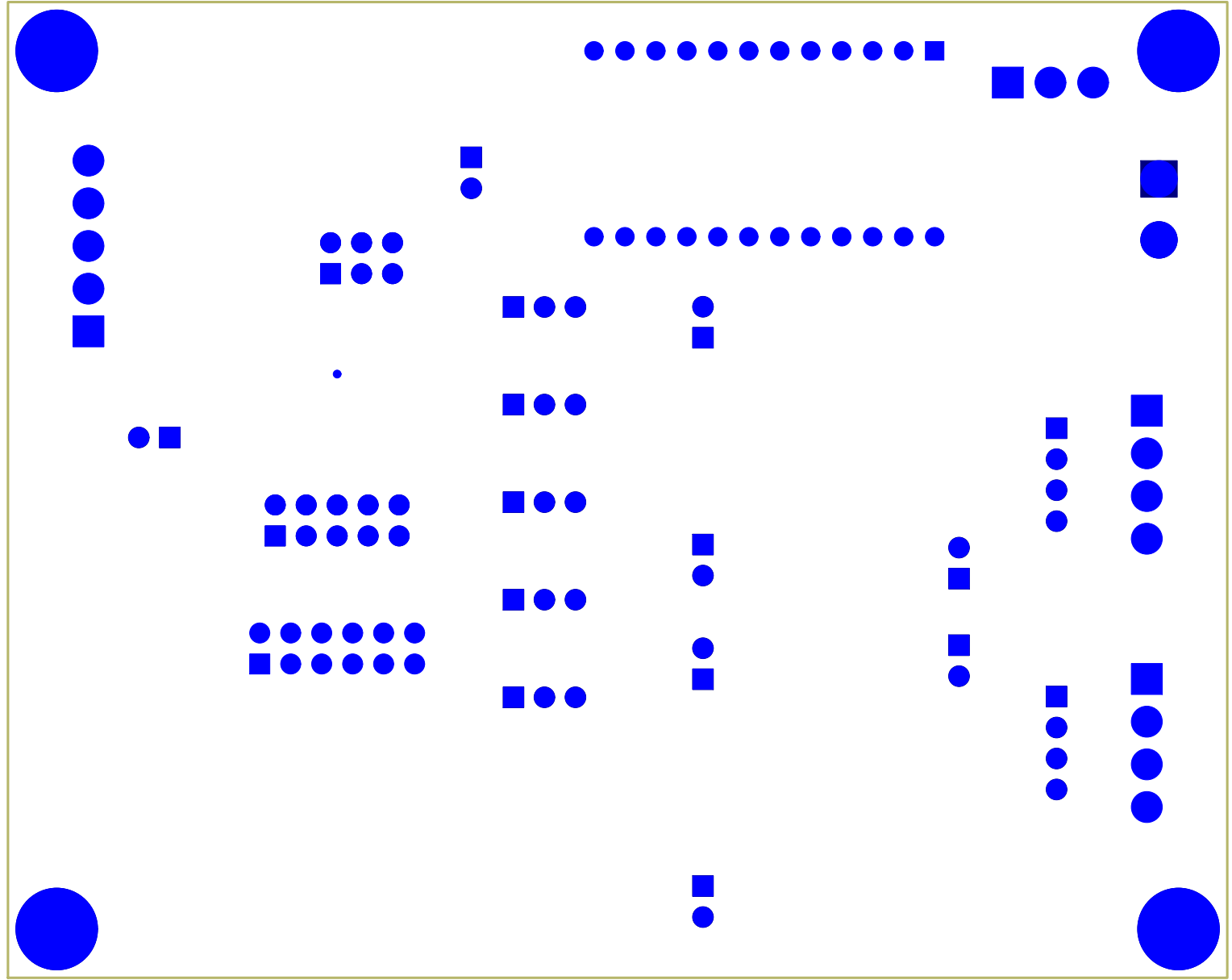
CCTV Reference Design 24.03.2011

ROUTING BOTTOM (L2)



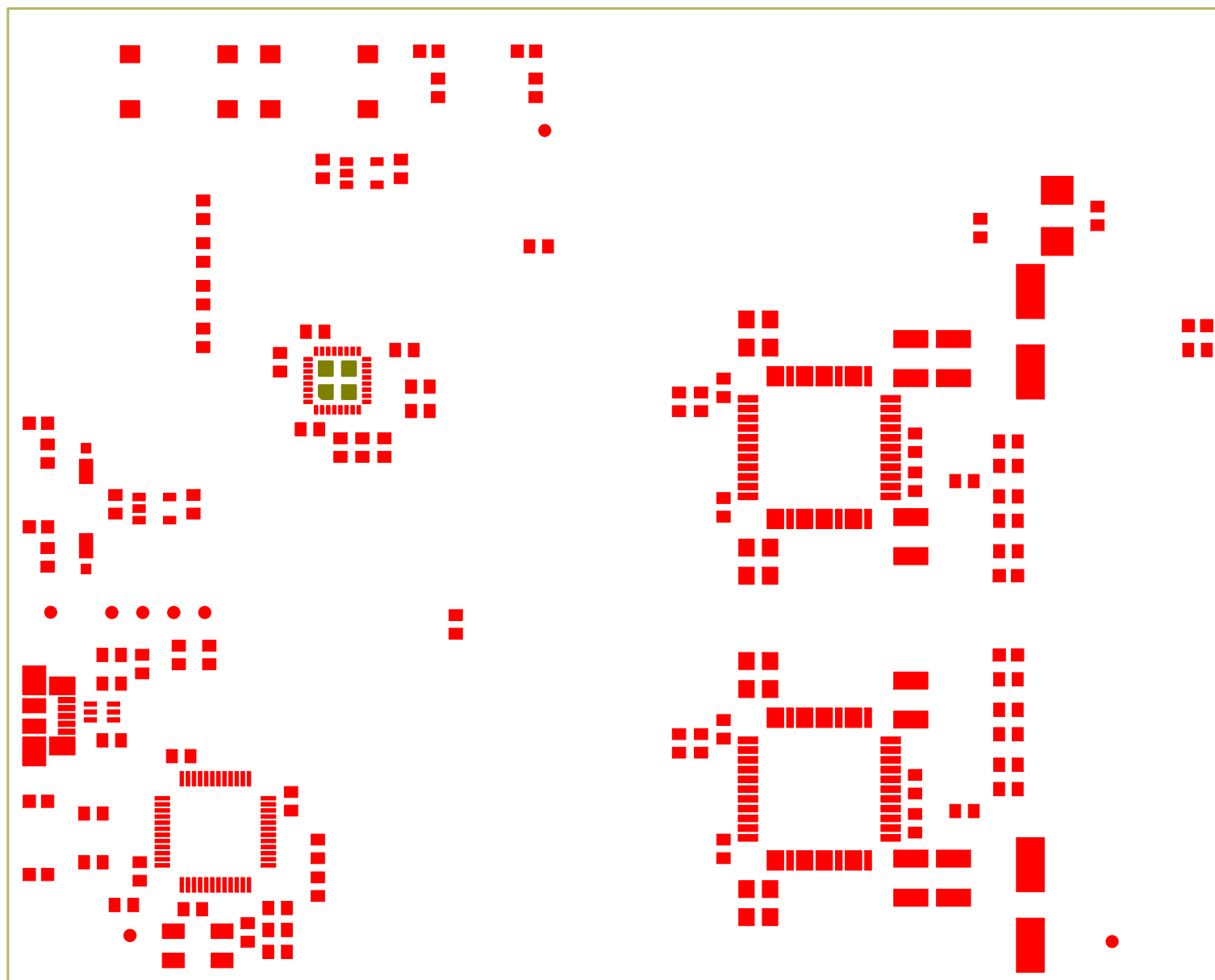
CCTV Reference Design 24.03.2011

SOLDER MASK TOP (L21)



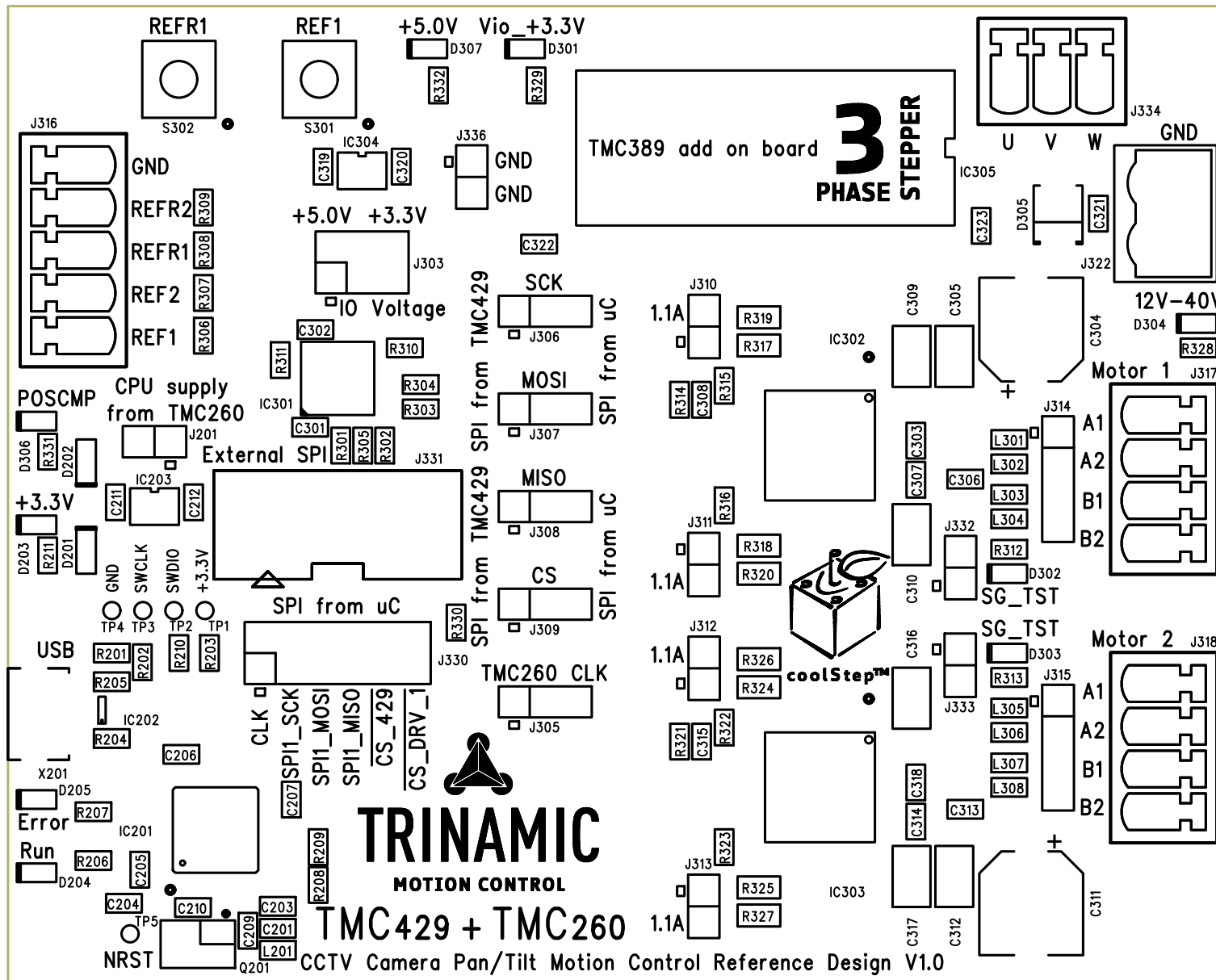
CCTV Reference Design 24.03.2011

SOLDER MASK BOTTOM (L58)



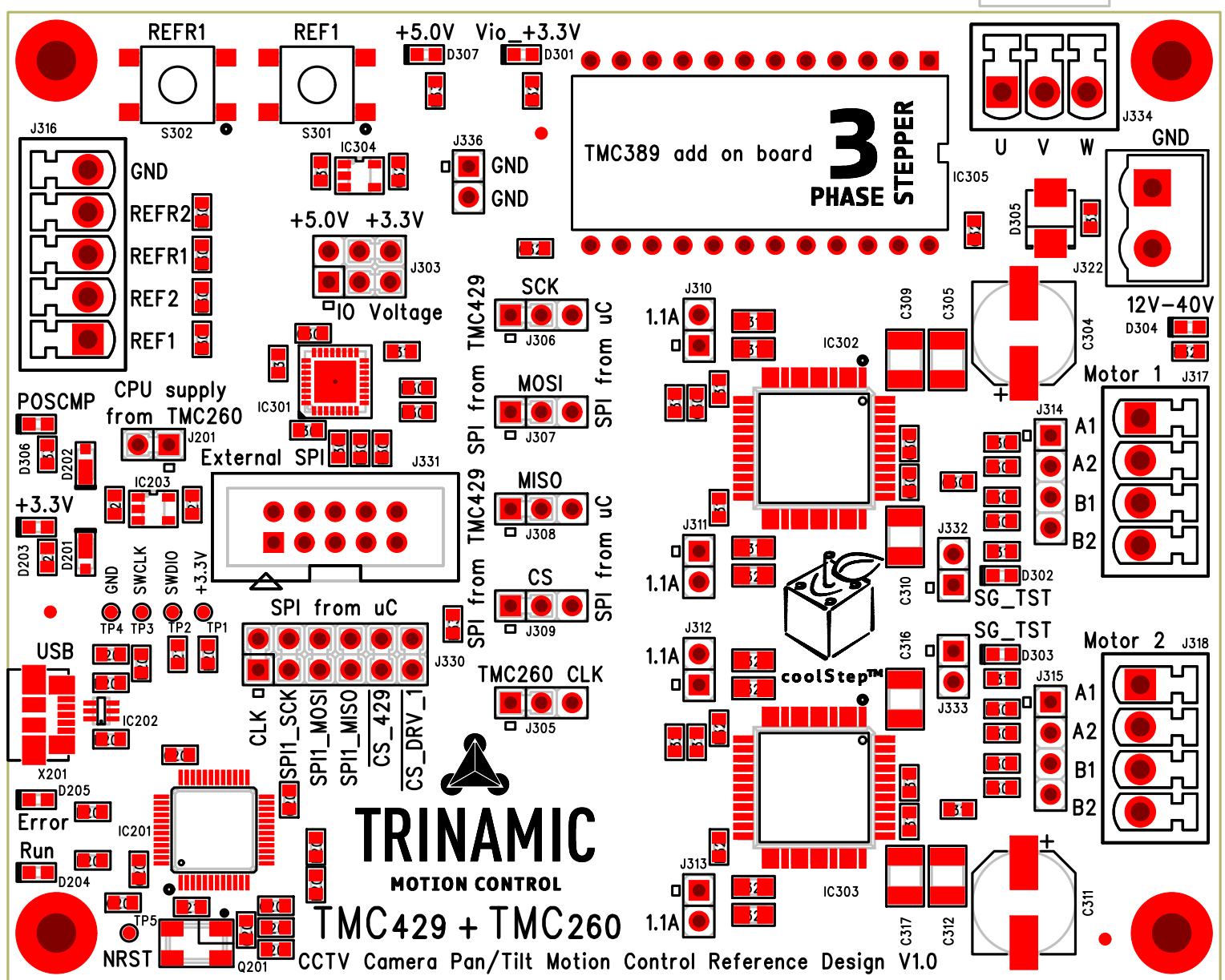
CCTV Reference Design 24.03.2011

PASTE MASK TOP (L23)



CCTV Reference Design 24.03.2011

SILKSCREEN TOP (L26)

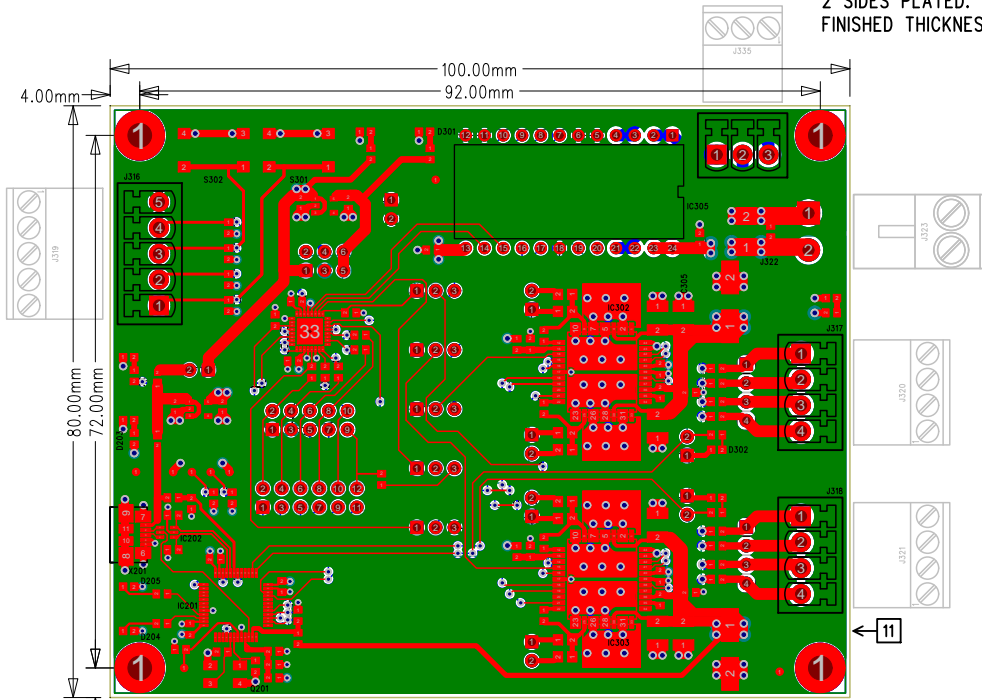


CCTV Reference Design 24.03.2011

SILKSCREEN TOP (L26) ROUTING TOP (L1) 100x80MM

NOTES : (UNLESS SPECIFIED OTHERWISE.)

- 1) ALL DIMENSIONS ARE IN INCHES. TOLERANCE IS +/- 0.005 CONFORMING TO IPC-A-600. GIVEN MECHANICAL DIMENSIONS ARE IN MILLIMETRES.
- 2) HOLE SIZES ARE SPECIFIED IN THOUSANDTHS. HOLE SIZES APPLY AFTER PLATING. HOLE SIZE TOLERANCE TO BE +/- 0.003, UNLESS SPECIFIED OTHERWISE. PLATING TO BE 0.0010 MINIMUM.
- 3) MATERIAL : FR-4- 2 NATURAL EPOXY/FIBERGLASS
35um COPPER ALL LAYERS.
2 SIDES PLATED.
FINISHED THICKNESS : 1.5 MM +/- 0.15 MM
- 4) APPLY SOLDERMASK OVER BARE COPPER, BOTH SIDES.
FINISH ALL EXPOSED COPPER SURFACES WITH IMMERSION GOLD.
- 5) THE LOCATION OF THE MARKING SHOULD BE ON THE SURFACE OF THE PCB, NOT THE EDGE.
- 6) APPLY SOLDERMASK TO COMPONENT SIDE AND SOLDER SIDE, USING
 - PC401 OR EQUIVALENT.
 - LIQUID PHOTO IMAGEABLE.
 - DRY FILM.
 COLOR : GREEN.
USE SEPARATE FILM FOR COMPONENT SIDE AND SOLDER SIDE SOLDERMASKS. FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO SOLDERMASK PLOTFILES FOR OPTIMAL SOLDERMASK COVERAGE BETWEEN FINE PITCH COMPONENT LEADS.
- 7) APPLY LEGEND TO TOP SIDE USING NON-CONDUCTIVE EPOXY INK. COLOR : WHITE. FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO LEGEND PLOTFILES TO ENSURE NO LEGEND INK COVERS ANY COMPONENT PAD OR VIA PAD.
- 8) PCB SHALL BE CLEAN AND FREE FROM DIRT, OIL, FINGERPRINTS, CORROSION, AND ANY OTHER FOREIGN MATERIAL.
- 9) MODIFIED PLOTFILES ARE TO BE RETURNED BEFORE ORDER DELIVERED.
- 10) BOW AND TWIST SHALL BE LESS THAN 0.0075" PER INCH.
- 11) ALL PRINTED CIRCUIT BOARD NETS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS. MARK TEST VERIFICATION STAMP APPROXIMATELY WHERE SHOWN, ALONG EDGE OF PCB, USING WHITE INK.
- 12) FABRICATION OF P.W.B. TO COMPLY WITH IPC-A-600, CLASS II , CURRENT REVISION.



CCTV Reference Design 24.03.2011

FABRICATION (L24)SILKSCREEN TOP (L26)ROUTING TOP (L1) 100x80MM
(S1) MOTTOB 3HTYOPPOWER LAYER 3 (L3)GROUND LAYER 2 (L2)
SOLDER MASK TOP (L21)(8S1) MOTTOB K2AM P2AM
PASTE MASK TOP (L23)

Top Side		
Cu-Foil with one-side Treatment	35um	Top Layer 1
Prepreg		
Prepreg		
FR4	35um	GND-Plane Layer 2
Prepreg		
Prepreg	35um	VCC-Plane Layer 3
Prepreg		
Cu-Foil with one-side Treatment	35um	Bottom Layer 4
Bottom Side		

0.059" +/- 0.0059
(1.5 mm +/- 0.15)

NOTICE: CONFIDENTIAL MATERIAL
Reproduction forbidden without the specific
written permission of Trinamic.

APPROVALS	DATE	TRINAMIC			
DRAWN: Elli Puusepp	24.03.2011	CCTV Reference Design FABRICATION			
CHECKED: M. Liik	24.03.2011				
PROJ MGR: Kaido Kevvai	24.03.2011				
CLIENT:	SIZE C	DRAWING NO: 8707002702	SCALE 1 : 1	SHEET 1 OF 1	REVISION 2